

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

### CERAMIC DIP 34, 50.8x50.8

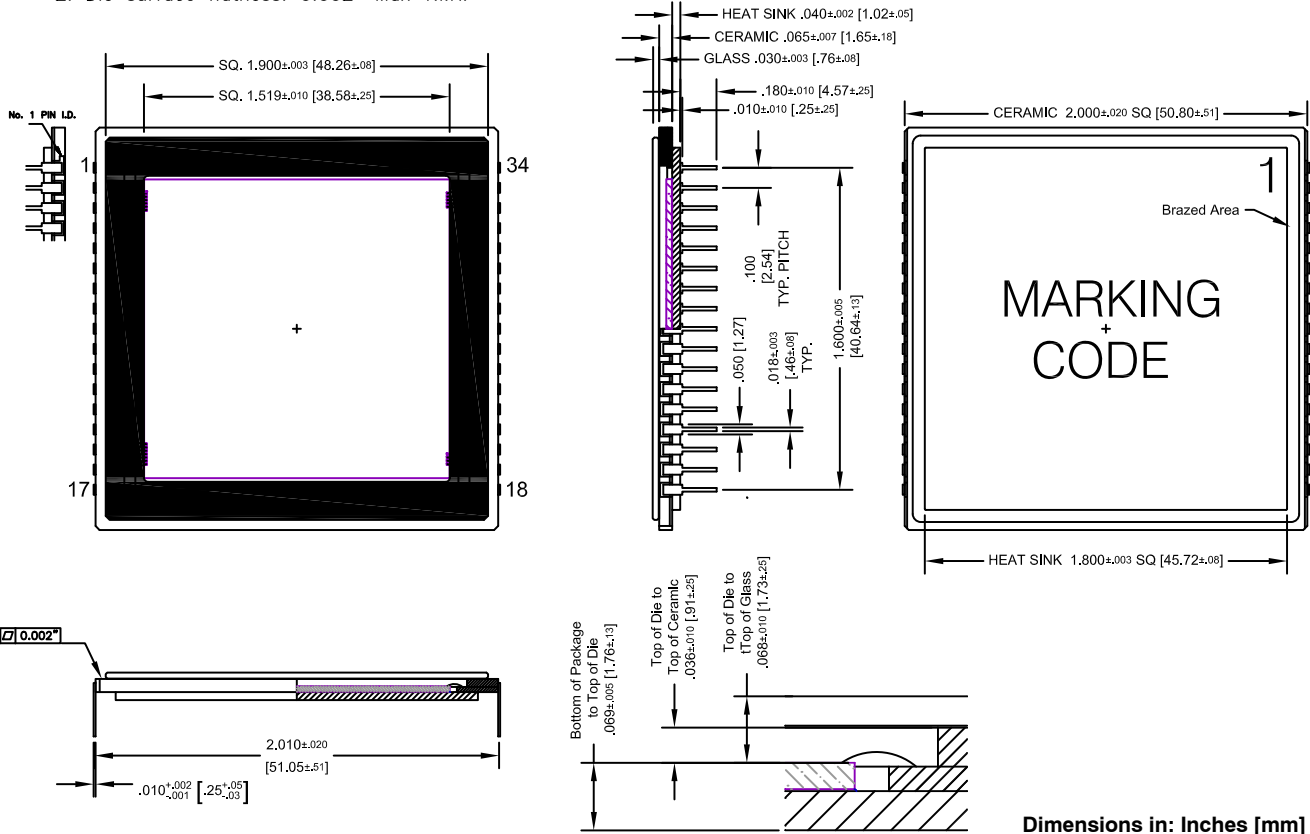
CASE 125BL  
ISSUE O

DATE 03 JUL 2014

**NOTES:**


1. Die is visually aligned within 1 degree of any package cavity edge.
2. Die surface flatness: 0.002" Max T.I.R.

SHOWN WITH SEALED COVER GLASS



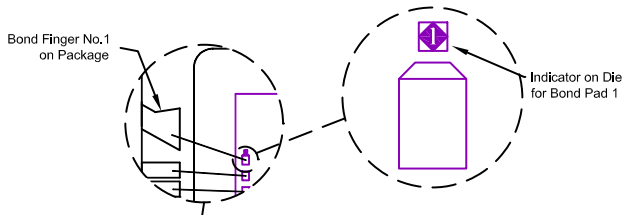
Dimensions in: Inches [mm]

|                         |                                  |   |
|-------------------------|----------------------------------|---|
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| <b>DESCRIPTION:</b>     | <b>CERAMIC DIP 34, 50.8x50.8</b> | <b>PAGE 1 OF 2</b>  |

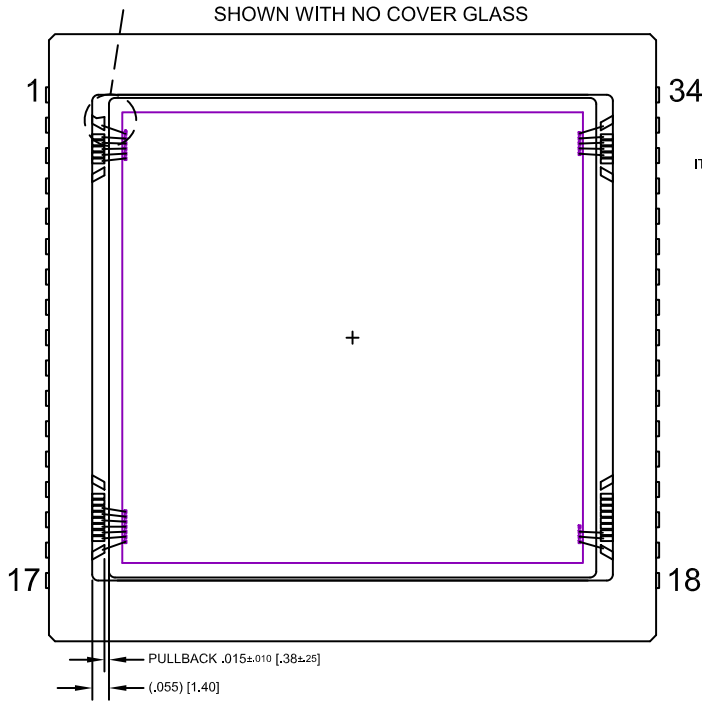
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**CERAMIC DIP 34, 50.8x50.8**  
**CASE 125BL**  
**ISSUE O**

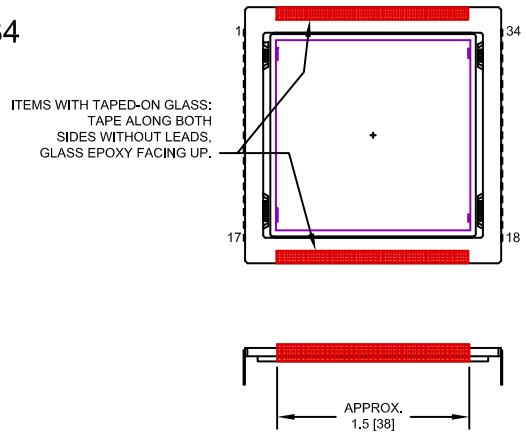
DATE 03 JUL 2014



- NOTES:
1. FOR SINGULATION PURPOSES: DIE ON WAFER ARE STEPPED (x) 38.60 mm, (y) 37.76 mm. ASSUMING 50 MICRON KERF, SINGULATED DIE ARE APPROXIMATELY 38.55 mm X 37.71 mm.
  2. WIRE LOOP HEIGHT: 0.014" +/- 0.003"
  3. TAPE USED TO TEMPORARILY HOLD ON GLASS IS PERMACEL P224 OR EQUIVALENT.



SHOWN WITH TAPED ON COVER GLASS



Dimensions in: Inches [mm]

|                         |                                  |  |
|-------------------------|----------------------------------|--|
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